

A

B

C

D

E

## ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.

Assembly shall conform with RoHS Directive 2011/65/EU.

Components shall be placed according to the associated CPL and BOM documents.

Lead-free SAC305 solder shall be used.

Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.

BGA components shall be 100% checked with x-ray for solder bridges after reflow.

Finished assemblies shall be removed from panel prior to delivery.

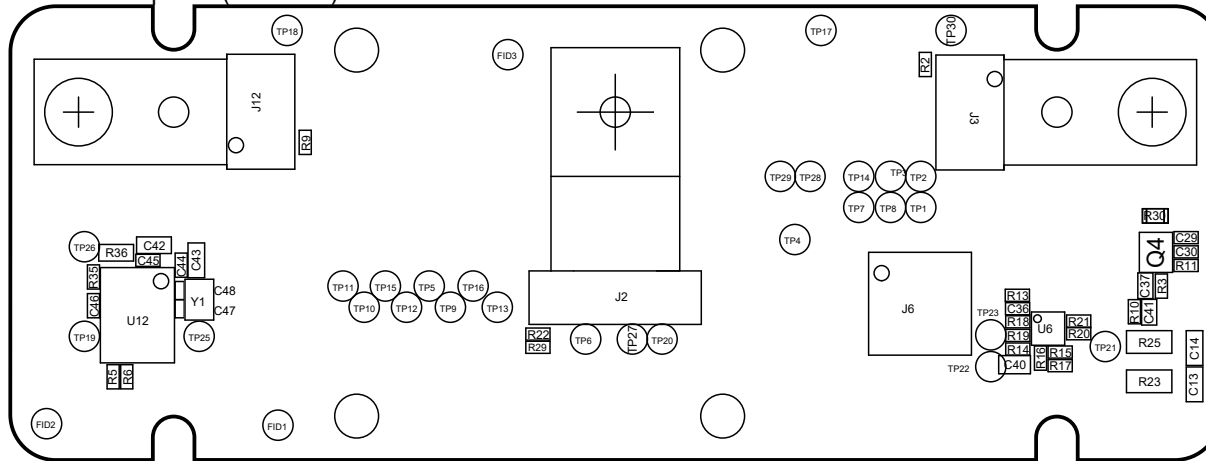
## Notes:

1 Note 1

2 Note 2

3 Note 3

View from Top side (Scale 2:1)

Title: **DM1095**

Number: DXXXX

Revision: ROM0  
E0

Date: 19/10/2021

Sheet: 1 of 2

Drawn by: David Malovrh

**LUXonjs**

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A

B

C

D

E

A

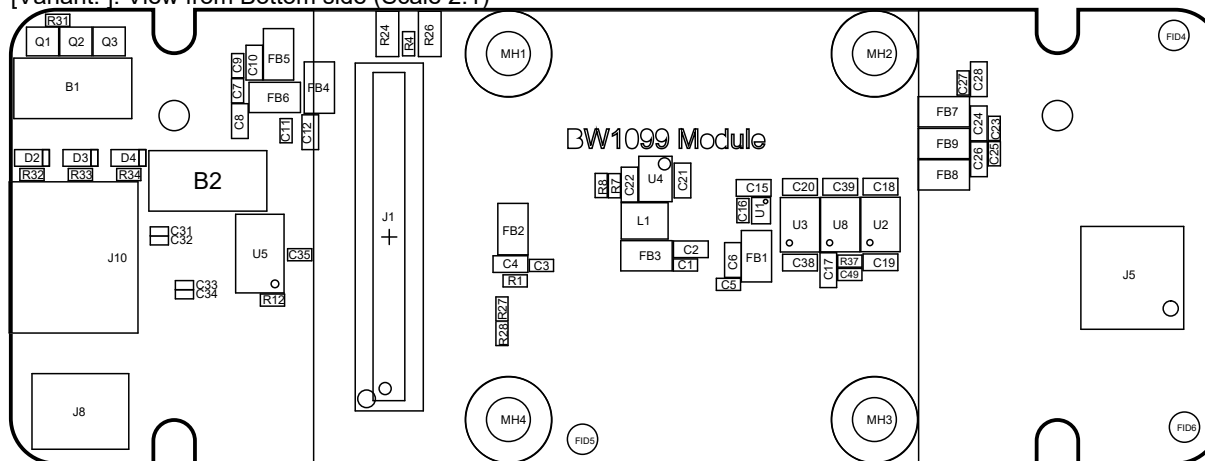
B

C

D

E

[Variant: ]: View from Bottom side (Scale 2:1)



Title: **DM1095**

Number: DXXXX

Revision: R0M0  
E0

Date: 19/10/2021

Sheet: 2 of 2

Drawn by: David Malovrh

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